

What Is Claimed Is:

1. An adhesive composition, comprising:

an insulating resin;

a photopolymerization initiator; and

an oxetan compound.

2. The adhesive composition according to Claim 1,  
comprising 5 to 50 wt% oxetan compound in 100 wt% adhesive  
composition.

3. The anisotropic conductive adhesive composition  
according to Claim 1 or Claim 2, further comprising  
electrically conductive particles.

4. A connected structure, wherein electrodes on a  
plastic substrate and on a circuit board that are facing each  
other are connected by the adhesive composition according to  
any of Claims 1 to 3.